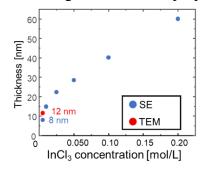
## In<sub>2</sub>O<sub>3</sub> Thin Films Deposited Using InCl<sub>3</sub> by Mist CVD Method

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In<sub>2</sub>O<sub>3</sub> is an oxide semiconductor with high transparency and conductivity, widely used in transparent conducting films and channel layers of thin-film transistors (TFTs). For application to high-mobility TFTs, we have been studying the deposition of  $\sim 10$  nm  $In_2O_3$ films on SiO<sub>2</sub>/Si substrates by the mist chemical vapor deposition (Mist CVD) method. Mist CVD is a technique in which the precursor solution is atomized by ultrasonic vibration and thermally decomposed on a heated substrate. The precursor solution is typically prepared by dissolving metal powders in an acidic solvent such as HCl. In our previous studies, it was confirmed that decreasing the HCl concentration in the solution during Mist CVD resulted in thinner In<sub>2</sub>O<sub>3</sub> films [1]. On the other hand, when the concentration approaches the solubility limit, undissolved In<sub>2</sub>O<sub>3</sub> powder remains, which negatively affects the film quality. To address this issue, we focused on InCl<sub>3</sub> as an alternative precursor. Since InCl<sub>3</sub> is easily soluble in deionized water, HCl is not required to prepare the solution, and it is expected that thinner In<sub>2</sub>O<sub>3</sub> films can be obtained simply by reducing the InCl<sub>3</sub> concentration [2]. In this study, In<sub>2</sub>O<sub>3</sub> thin films were deposited on SiO<sub>2</sub>/Si substrates by Mist CVD using InCl<sub>3</sub> solutions with concentrations between 0.0050 and 0.20 mol/L. The solutions were used after visually confirming complete dissolution by visual inspection.

Figure 1 shows the film thickness as a function of InCl<sub>3</sub> concentration measured using SE and TEM. The results show that the In<sub>2</sub>O<sub>3</sub> films became thinner as the InCl<sub>3</sub> concentration decreased. An In<sub>2</sub>O<sub>3</sub> film thickness of about 10 nm was achieved at the concentration of 0.0050 mol/L. Figure 2 shows the bird's-eye FE-SEM images of In<sub>2</sub>O<sub>3</sub> films grown at the InCl<sub>3</sub> concentrations of 0.0050 and 0.20 mol/L. At the concentration of 0.0050 mol/L, the smoother surface was obtained with smaller crystal grain sizes, while at 0.20 mol/L, the three-dimensional surface was obtained with large crystal grain sizes. The flattening of the surface with decreasing InCl<sub>3</sub> concentration can be explained by the smaller grain size. In the presentation, we will comprehensively discuss the structure of the grown In<sub>2</sub>O<sub>3</sub> thin films, including their electrical properties.



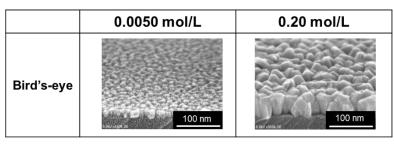


Figure 1. In<sub>2</sub>O<sub>3</sub> film thickness using SE and TEM.

Figure 2. Bird's-eye FE-SEM images of In<sub>2</sub>O<sub>3</sub> films grown at InCl<sub>3</sub> concentrations of 0.20 and 0.0050 mol/L.

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